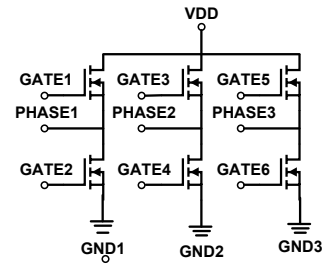
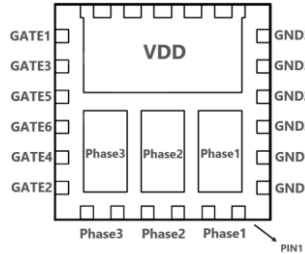


## Main Product Characteristics

$BV_{DSS}$	40V
$R_{DS(ON)}$	2.2m $\Omega$
$I_D$	150A



## Features and Benefits

- Advanced MOSFET process technology
- Ideal for 3-phase motor driver or inverter
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSMP04150 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	40	V
Gate-Source Voltage	V <sub>GS</sub>	+20/-12	V
Drain Current-Continuous (T <sub>c</sub> =25°C)	I <sub>D</sub>	150	A
Drain Current-Continuous (T <sub>c</sub> =100°C)		95	
Drain Current-Pulsed <sup>1</sup>	I <sub>DM</sub>	600	A
Single Pulse Avalanche Energy <sup>2</sup>	E <sub>AS</sub>	320	mJ
Single Pulse Avalanche Current <sup>2</sup>	I <sub>AS</sub>	80	A
Power Dissipation (T <sub>c</sub> =25°C)	P <sub>D</sub>	86	W
Power Dissipation-Derate above 25°C		1.45	
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	5.06	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 To +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 To +150	°C

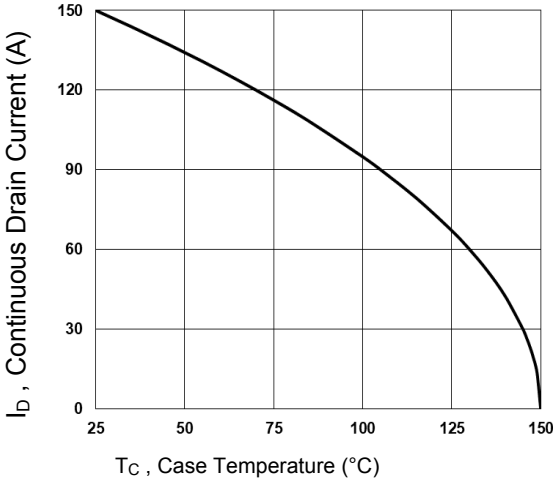
### Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1	$\mu A$
		$V_{DS}=32V, V_{GS}=0V, T_J=85^\circ\text{C}$	-	-	10	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}^3$	$V_{GS}=10V, I_D=40A$	-	1.8	2.2	m $\Omega$
	$R_{DS(ON)}^4$	$V_{GS}=10V, I_D=40A$	-	2.2	2.6	
	$R_{DS(ON)}^5$	$V_{GS}=10V, I_D=40A$	-	2.8	3.5	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0	2.8	4.0	V
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=5A$	-	15	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>6,7</sup>	$Q_g$	$V_{DS}=20V, I_D=70A, V_{GS}=10V$	-	58.4	88	nC
Gate-Source Charge <sup>6,7</sup>	$Q_{gs}$		-	14.3	21.5	
Gate-Drain Charge <sup>6,7</sup>	$Q_{gd}$		-	12.0	20	
Turn-On Delay Time <sup>6,7</sup>	$t_{d(on)}$	$V_{DD}=20V, R_G=6\Omega, V_{GS}=10V, I_D=1A$	-	14.6	-	nS
Rise Time <sup>6,7</sup>	$t_r$		-	21.5	-	
Turn-Off Delay Time <sup>6,7</sup>	$t_{d(off)}$		-	52	-	
Fall Time <sup>6,7</sup>	$t_f$		-	83.5	-	
Input Capacitance	$C_{iss}$	$V_{DS}=20V, V_{GS}=0V, F=1\text{MHz}$	-	3310	4965	pF
Output Capacitance	$C_{oss}$		-	1090	1650	
Reverse Transfer Capacitance	$C_{rss}$		-	100	150	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	150	A
Pulsed Source Current	$I_{SM}$		-	-	300	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	-	-	1	V
Reverse Recovery Time	$t_{rr}$	$V_R=30V, I_S=10A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$	-	38	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	90	-	nC

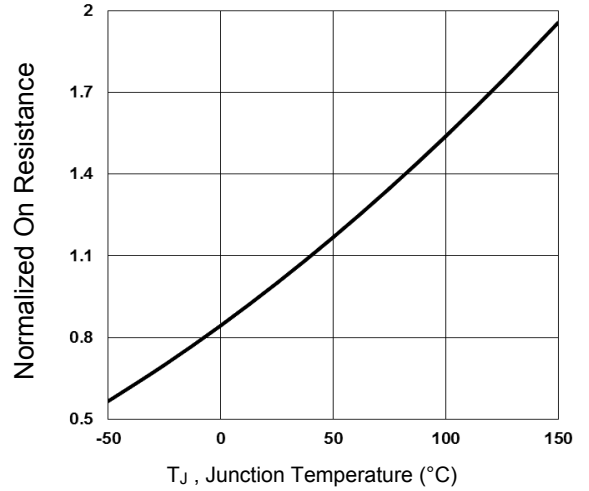
Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=80A, R_G=25\Omega$ , starting  $T_J=25^\circ\text{C}$ .
3. The  $R_{DS(ON)}$  value is the position of M1, M2, M3 and M5.
4. The  $R_{DS(ON)}$  value is the position of M4.
5. The  $R_{DS(ON)}$  value is the position of M6.
6. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
7. Essentially independent of operation temperature.

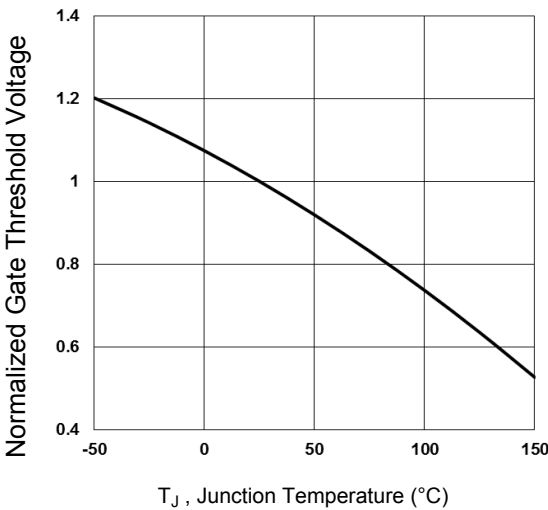
**Typical Electrical and Thermal Characteristic Curves**



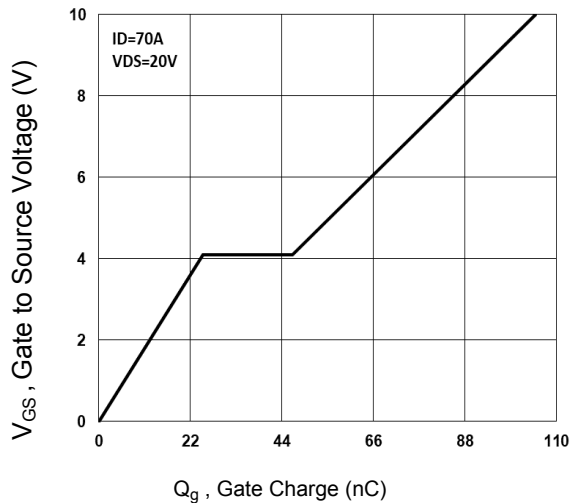
**Fig.1 Continuous Drain Current vs. Tc**



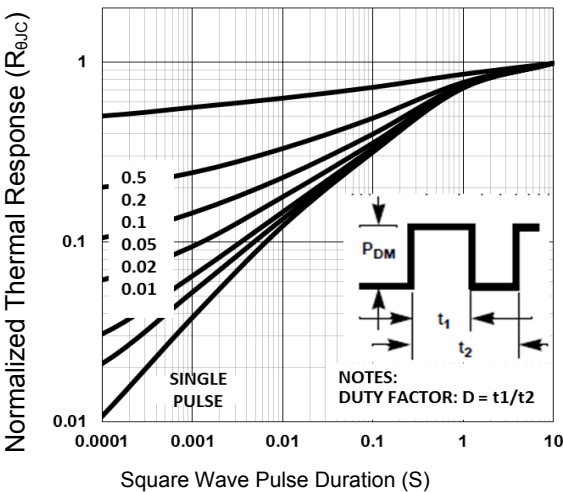
**Fig.2 Normalized  $R_{DS(ON)}$  vs.  $T_J$**



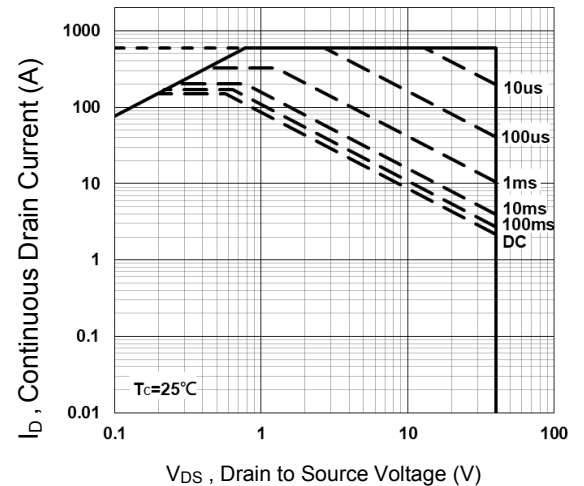
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.4 Gate Charge Waveform**



**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

**Typical Electrical and Thermal Characteristic Curves**

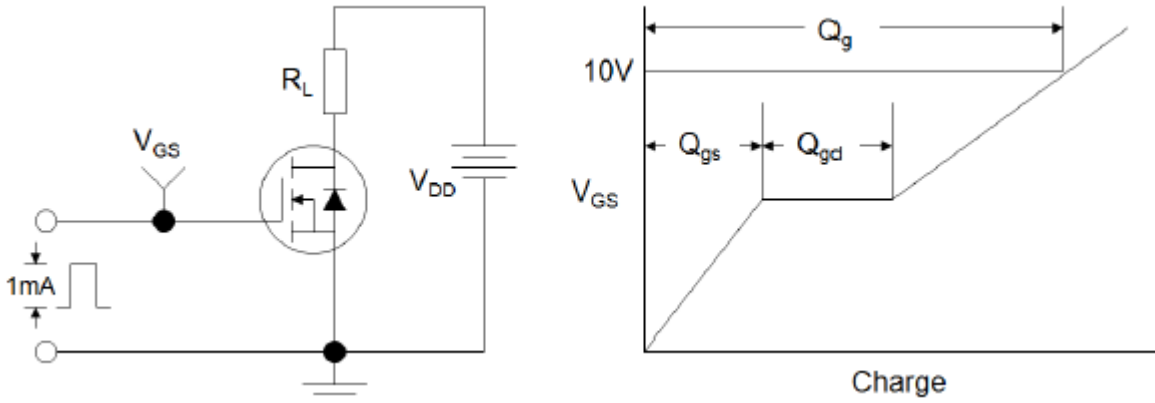


Figure 7. Gate Charge Test Circuit & Waveform

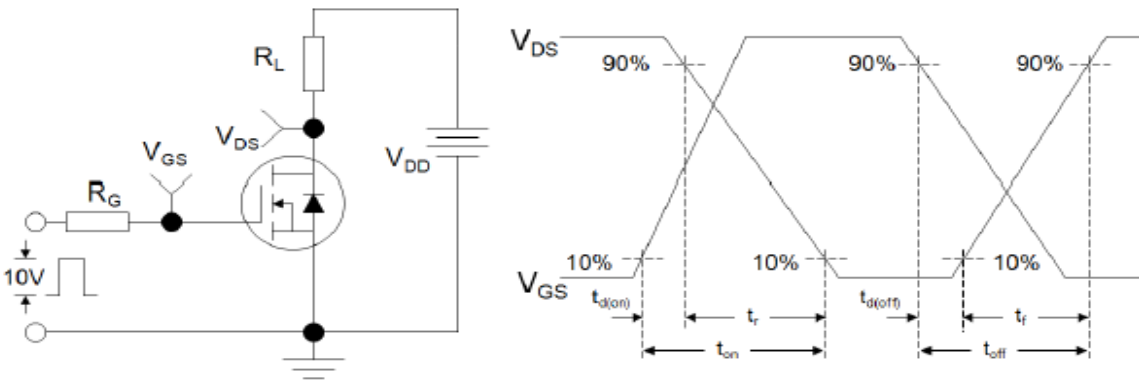


Figure 8. Resistive Switching Test Circuit & Waveforms

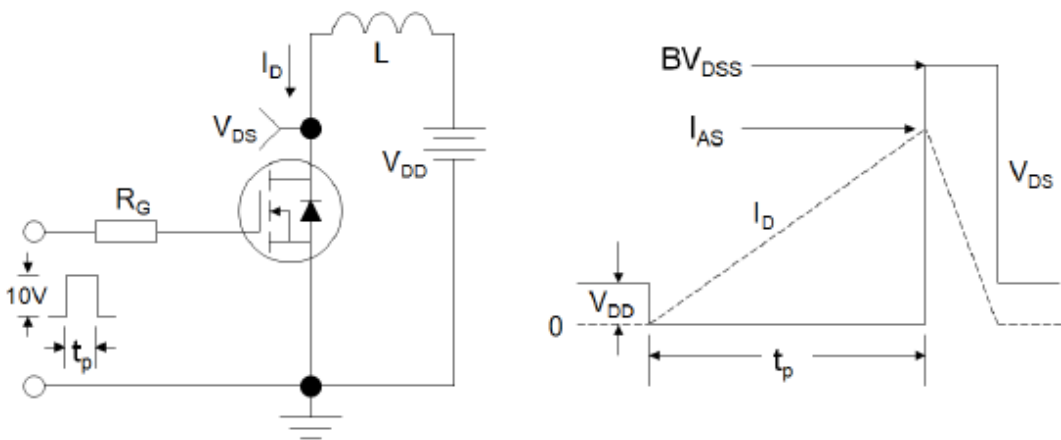
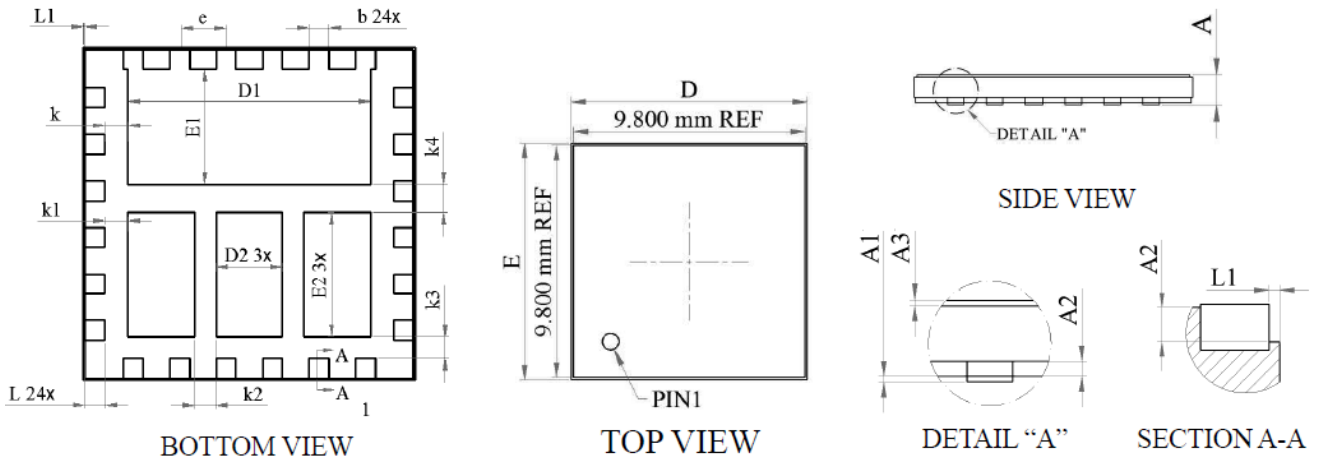


Figure 9.  $E_{AS}$  Circuit & Waveforms

### Package Outline Dimensions

### DFN10x10



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min	Normal	Max	Min	Normal	Max
A	0.950	-	1.050	0.038	-	0.041
A1	-	-	0.005	-	-	0.000
A2	0.080	-	0.250	0.003	-	0.010
A3	0.050	0.075	0.100	0.002	0.003	0.004
D	9.900	10.000	10.100	0.390	0.394	0.398
E	9.900	10.000	10.100	0.390	0.394	0.398
D1	7.200	7.300	7.400	0.283	0.287	0.291
E1	3.350	3.450	3.550	0.132	0.136	0.140
D2	1.900	2.000	2.100	0.075	0.079	0.083
E2	3.650	3.750	3.850	0.144	0.148	0.152
b	0.500	0.600	0.700	0.020	0.024	0.028
L	0.500	0.600	0.700	0.020	0.024	0.028
L1	0.010	0.050	0.090	0.000	0.002	0.004
k	0.700 REF			0.028 REF		
k1	0.700 REF			0.028 REF		
k2	0.650 REF			0.026 REF		
k3	0.650 REF			0.026 REF		
k4	0.850 REF			0.033 REF		
e	1.400 BSC			0.055 BSC		